



LPCAMM2

Featuring a new memory form factor, it promises to bridge PC and mobile memory application scenarios. It has four x32 LPDDR5/5X soldered onto a single memory module and connects to the motherboard via a high-speed connector. It achieves a 128-bit memory bus on a single module, opening new design possibilities for AI terminals, commercial-use devices, ultra-thin laptops, and other scenarios requiring high speed, low power consumption, and miniaturized packaging.

Product Features

- Compatible with 315-ball and 496-ball LPDDR5/5x designs
- More than 50% lower power consumption than DDR5 SODIMMs
- Large PCB grounding area for improving heat dissipation
- Upgradable, low maintenance cost
- Supports over 7,500MT/s
- Saves over 60% space compared to SODIMMs
- High-speed contact connector for stable connection and better ESD protection

Applications



AI terminals



HPCs



Ultra-thin laptops

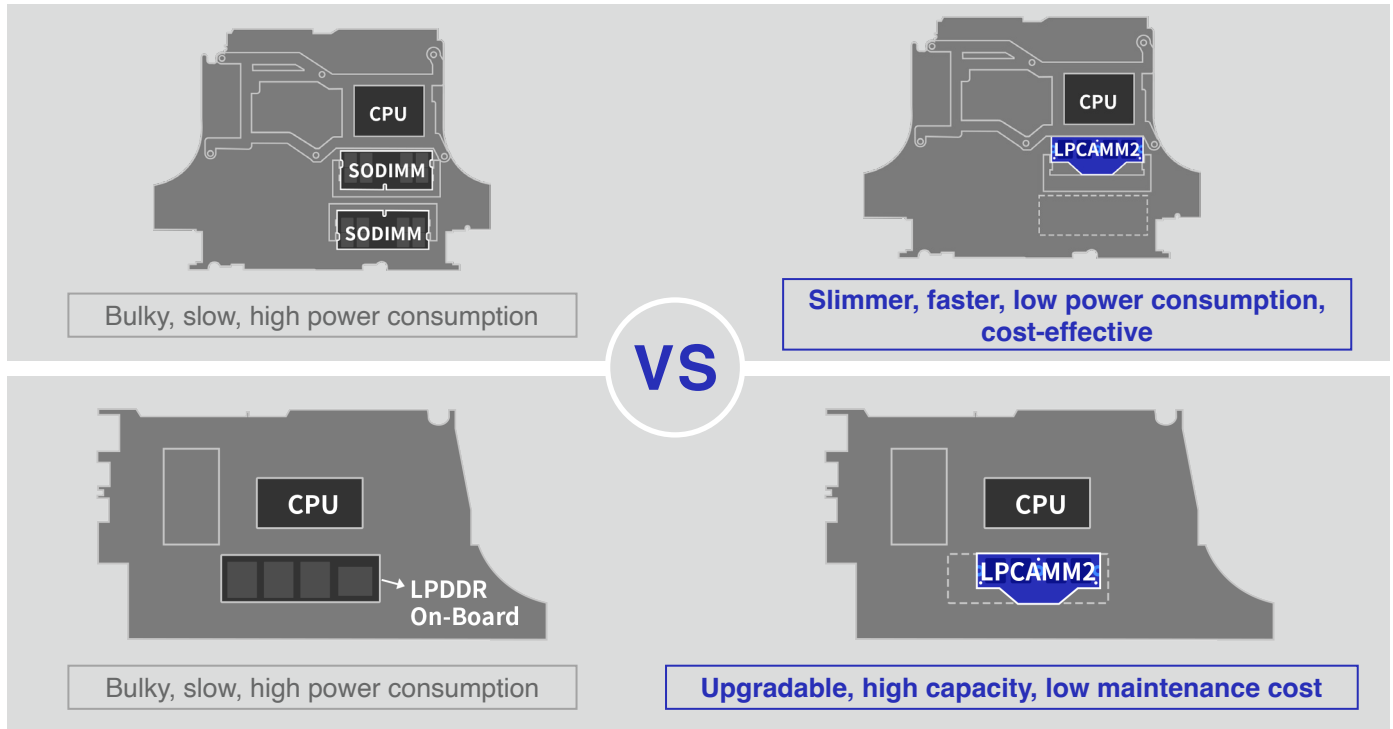


Commercial-use
devices

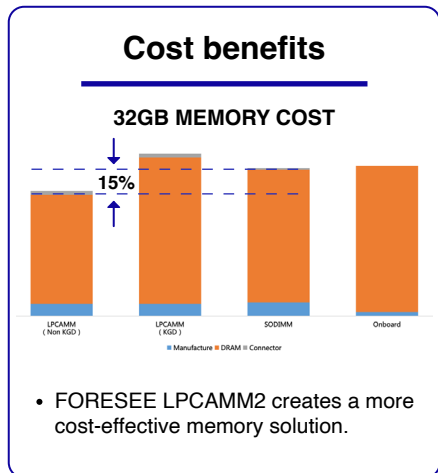


Workstations

LPCAMM2 vs. Traditional Memory



Advantages



Environmental requirements

- Meets new EU regulations.
- Upgradable, and the low maintenance cost better satisfies EU environmental demands.

Motherboard design

ON-Board DRAM LPCAMM2

- Unified LPCAMM2 interface significantly reduces the complex high-speed parallel DRAM traces.
- Can reduce motherboard layer count.

LPCAMM2 Line-up

Product Series	Interface	DRAM	Capacity	Architecture	Data Rate	Band Width	Operating Voltage	Operating Temperature	Size
LPCAMM2	CAMM2	x32 315ball LPDDR5/5X	16GB	1R×16	6400Mbps	128bit (x16, 8 subchannels)	VIN BULK 4.25V~5.5V	0°C~85°C	78*23 mm
LPCAMM2	CAMM2	x32 315ball LPDDR5/5X	32GB	1R×16	7500Mbps	128bit (x16, 8 subchannels)	VIN BULK 4.25V~5.5V	0°C~85°C	78*23 mm

*Data is sourced from internal testing of Longsys. The actual performance may vary between different devices.



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